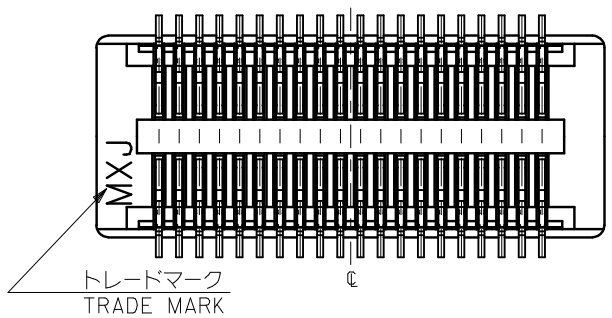


30極以下品形状
SHAPE OF 30 CIRCUITS OR LESS

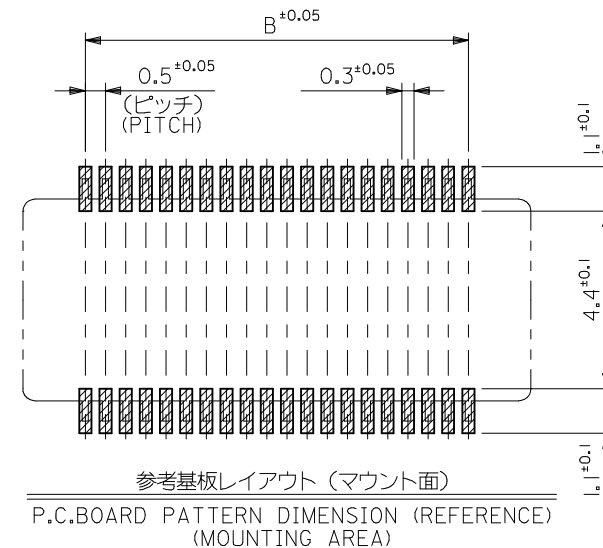
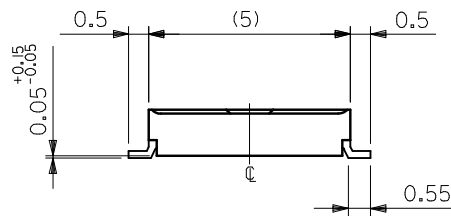
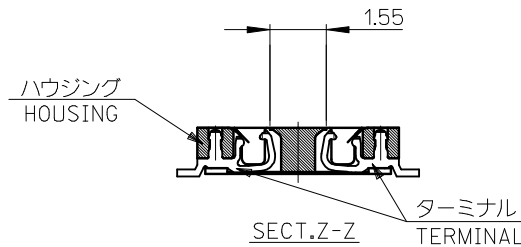
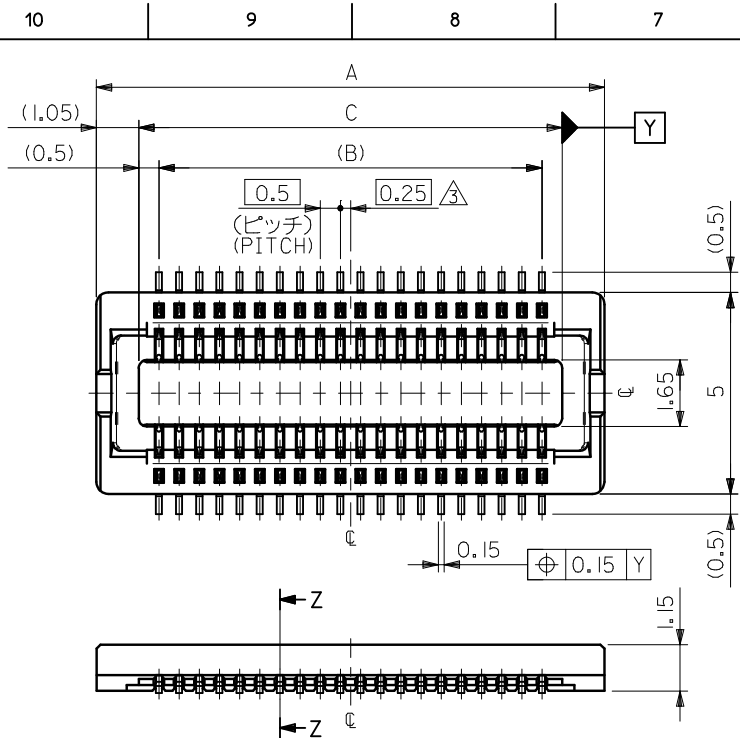


- 注記 NOTES:
1. 使用材料 MATERIAL
 ハウジング: 液晶ポリマー ガラス充填、UL94V-0 (黒)
 HOUSING: LIQUID CRYSTAL POLYMER (GLASS FILLED)
 UL94V-0, (COLOR: BLACK)
 ターミナル: リン青銅 (t=0.15)
 TERMINAL: PHOSPHOR BRONZE (t=0.15)
 2. メッキ仕様 PLATING
 金メッキ 0.25マイクロメートル以上 (コンタクト部)
 GOLD 0.25 MICROMETER MINIMUM (CONTACT AREA)
 金メッキ 0.4マイクロメートル以下 (テール部)
 GOLD 0.4 MICROMETER MAXIMUM (TAIL AREA)
 下地メッキ: ニッケルメッキ 1.5マイクロメートル以上
 UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM
 *コンタクト部とテール部はニッケルメッキによって
 分断されている金メッキです。
 DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT
 AND THE TAIL PART BY THE NICKEL PLATING.

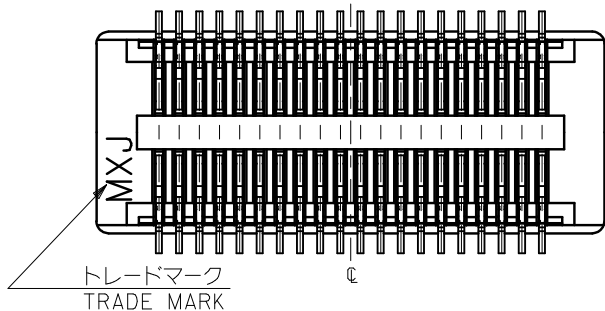
- ③ (全極数/2) = 偶数の場合に適用。
 APPLY FOR (CIRCUIT/2) = EVEN.
4. 嵌合相手: 55560シリーズ, 53794シリーズ
 MATE WITH: 55560 SERIES, 53794 SERIES.
 5. テール平坦度は、0.1以下
 TAIL COPLANARITY TO BE 0.1 MAXIMUM.

8.0	7.0	10.1	54722-0304	54722-0303	30
6.5	5.5	8.6	54722-0244	54722-0243	24
6.0	5.0	8.1	54722-0224	54722-0223	22
5.5	4.5	7.6	54722-0204	54722-0203	20
4.5	3.5	6.6	54722-0164	54722-0163	16
C	B	A	EMBSTP PKG. ORDER No. オーダー番号	MATERIAL No.	極数 CIRCUIT

REVISED EC NO: J2017-0400 DRWN: FURUKAWA 2017/01/30 CHKD: TASAKAWA 2017/01/31 APPR: KUSUHARA01 2017/04/11	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO. 54722-***3
	0.25 UNDER	UNDER	±0.2	DRAWN BY T. ITO	DATE '03/08/20	TITLE 0.5 B-TO-B CONN REC ASSY [NI BARRIER] (HGT=1.5) -LEAD FREE- molex	SHEET NO. 1 OF 2
	0.25 OVER	0.5 UNDER	±0.2	CHECKED BY T. YAMAGUCHI	DATE '03/08/20		
	0.5 OVER	1.0 UNDER	±0.2	APPROVED BY T. YAMAGUCHI	DATE '03/08/20		
	1.0 OVER	30 UNDER	±0.25	MATERIAL NO.	DOCUMENT NO.		
30 OVER		±0.3	SEE CHART		SD-54722-011		
	ANGULAR	±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



30極以下品形状
SHAPE OF 30 CIRCUITS OR LESS



注記 NOTES:

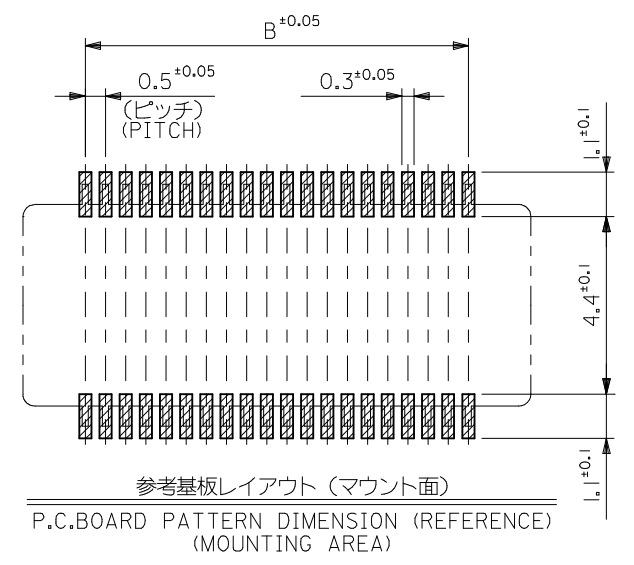
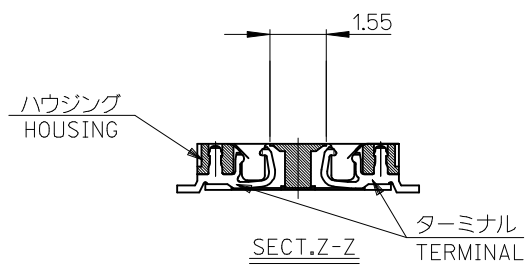
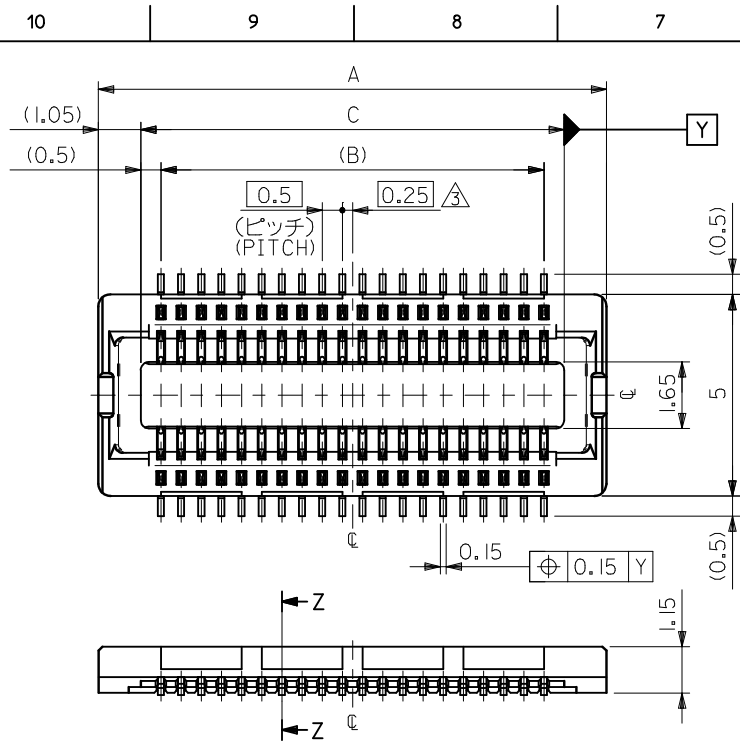
- 使用材料 MATERIAL
ハウジング: 液晶ポリマー ガラス充填、UL94V-0 (黒)
HOUSING: LIQUID CRYSTAL POLYMER (GLASS FILLED)
UL94V-0, (COLOR: BLACK)
ターミナル: リン青銅 (t=0.15)
TERMINAL: PHOSPHOR BRONZE (t=0.15)
- メッキ仕様 PLATING
金メッキ 0.25マイクロメートル以上 (コンタクト部)
GOLD 0.25 MICROMETER MINIMUM (CONTACT AREA)
金メッキ 0.4マイクロメートル以下 (テール部)
GOLD 0.4 MICROMETER MAXIMUM (TAIL AREA)
下地メッキ: ニッケルメッキ 1.5マイクロメートル以上
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM
*コンタクト部とテール部はニッケルメッキによって
分断されている金メッキです。
DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT
AND THE TAIL PART BY THE NICKEL PLATING.

- ③ (全極数/2) = 偶数の場合に適用。
APPLY FOR (CIRCUIT/2) = EVEN.
- 嵌合相手: 55560シリーズ, 53794シリーズ
MATE WITH: 55560 SERIES, 53794 SERIES.
 - テール平坦度は、0.1以下
TAIL COPLANARITY TO BE 0.1 MAXIMUM.

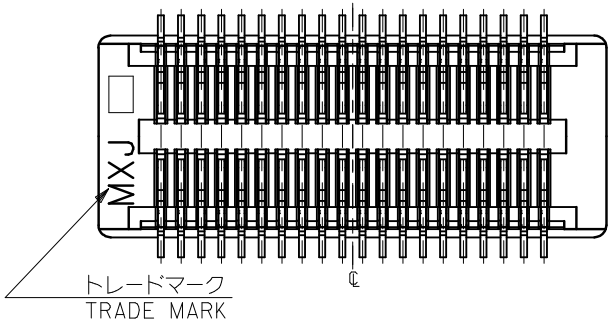
8.0	7.0	10.1	54722-0304	54722-0303	30
6.5	5.5	8.6	54722-0244	54722-0243	24
6.0	5.0	8.1	54722-0224	54722-0223	22
5.5	4.5	7.6	54722-0204	54722-0203	20
4.5	3.5	6.6	54722-0164	54722-0163	16
C	B	A	EMBSTP PKG. ORDER No. オーダー番号	MATERIAL No.	極数 CIRCUIT

MODEL NO. 54722-***3

REVISED EC NO: J2017-0400 DRWN: FURUKAWA 2017/01/30 CHKD: TASAKAWA 2017/01/31 APPR: KUSUHARA01 2017/04/11	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	0.25 UNDER	UNDER	±0.2	DRAWN BY	DATE	TITLE			
	0.25 OVER	0.5 UNDER	±0.2	T. ITO	'03/08/20	0.5 B-TO-B CONN REC ASSY [NI BARRIER] (HGT=1.5) -LEAD FREE-			
	0.5 OVER	1.0 UNDER	±0.2	CHECKED BY	DATE	molex			
	1.0 OVER	30 UNDER	±0.2	T. YAMAGUCHI	'03/08/20				
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE	DOCUMENT NO.		SHEET NO.		
30 OVER		±0.3	T. YAMAGUCHI	'03/08/20	SD-54722-011		1 OF 2		
ANGULAR	±3 °		MATERIAL NO.		SEE CHART				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



34極以上品形状
SHAPE OF 34CIRCUITS OR MORE



注記 NOTES:

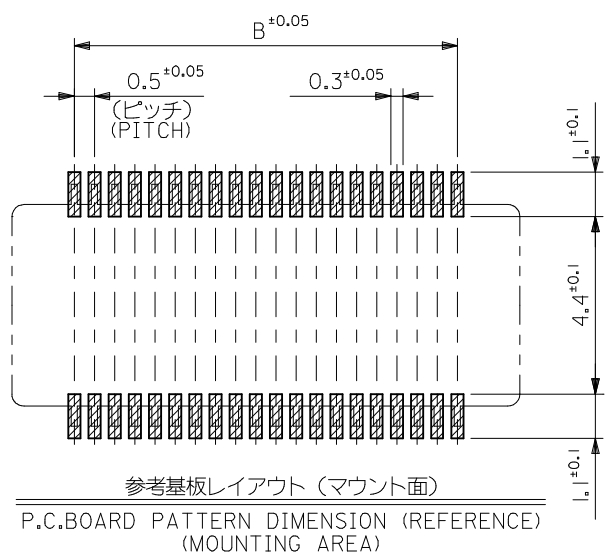
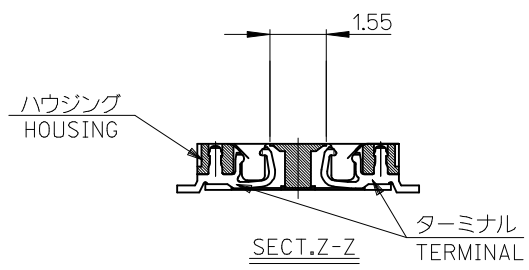
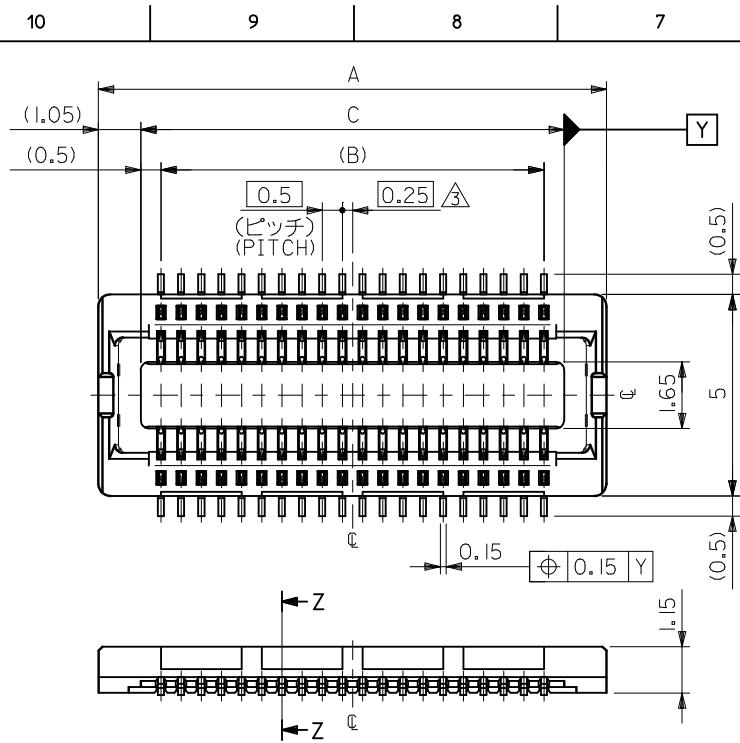
- 使用材料 MATERIAL
ハウジング: 液晶ポリマー ガラス充填, UL94V-0 (黒)
HOUSING: LIQUID CRYSTAL POLYMER (GLASS FILLED)
UL94V-0, (COLOR:BLACK)
ターミナル: リン青銅 (t=0.15)
TERMINAL: PHOSPHOR BRONZE (t=0.15)
- メッキ仕様 PLATING
金メッキ 0.25マイクロメートル以上 (コンタクト部)
GOLD 0.25 MICROMETER MINIMUM (CONTACT AREA)
金メッキ 0.4マイクロメートル以下 (テール部)
GOLD 0.4 MICROMETER MAXIMUM (TAIL AREA)
下地メッキ: ニッケルメッキ 1.5マイクロメートル以上
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM
*コンタクト部とテール部はニッケルメッキによって
分断されている金メッキです。
DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT
AND THE TAIL PART BY THE NICKEL PLATING.

△ (全極数/2) = 偶数の場合に適用。
APPLY FOR (CIRCUIT/2)=EVEN.

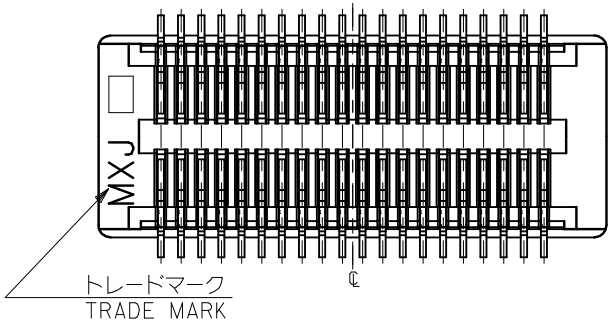
- 嵌合相手: 55560シリーズ, 53794シリーズ
MATE WITH: 55560 SERIES, 53794 SERIES.
- テール平坦度は、0.1以下
TAIL COPLANARITY TO BE 0.1 MAXIMUM.

20.5	19.5	22.6	54722-0804	54722-0803	80
15.5	14.5	17.6	54722-0604	54722-0603	60
13.0	12.0	15.1	54722-0504	54722-0503	50
10.5	9.5	12.6	54722-0404	54722-0403	40
9.0	8.0	11.1	54722-0344	54722-0343	34
C	B	A	EMBSTP PKG. ORDER No. オーダー番号	MATERIAL No.	極数 CIRCUIT

REVISED EC NO: J2017-0400 DRWN: FURUKAWA 2017/01/30 CHKD: TASAKAWA 2017/01/31 APPR: KUSUHARA01 2017/04/11	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO. 54722-***3
	0.25 UNDER	UNDER	±0.2	DRAWN BY T. ITO	DATE '03/08/20	TITLE 0.5 B-TO-B CONN REC ASSY [NI BARRIER] (HGT=1.5) -LEAD FREE-	THIRD ANGLE PROJECTION
	0.25 OVER	0.5 UNDER	±0.2	CHECKED BY T. YAMAGUCHI	DATE '03/08/20	molex	DOCUMENT NO. SD-54722-011
	0.5 OVER	1.0 UNDER	±0.2	APPROVED BY T. YAMAGUCHI	DATE '03/08/20		
	1.0 OVER	30 UNDER	±0.2	MATERIAL NO.		SEE CHART	
30 OVER		±0.3	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
	ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				



34極以上品形状
SHAPE OF 34CIRCUITS OR MORE



注記 NOTES:
1. 使用材料 MATERIAL
ハウジング: 液晶ポリマー ガラス充填, UL94V-0 (黒)
HOUSING: LIQUID CRYSTAL POLYMER (GLASS FILLED)
UL94V-0, (COLOR:BLACK)
ターミナル: リン青銅 (t=0.15)
TERMINAL: PHOSPHOR BRONZE (t=0.15)
2. メッキ仕様 PLATING
金メッキ 0.25マイクロメートル以上 (コンタクト部)
GOLD 0.25 MICROMETER MINIMUM (CONTACT AREA)
金メッキ 0.4マイクロメートル以下 (テール部)
GOLD 0.4 MICROMETER MAXIMUM (TAIL AREA)
下地メッキ: ニッケルメッキ 1.5マイクロメートル以上
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM
*コンタクト部とテール部はニッケルメッキによって
分断されている金メッキです。
DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT
AND THE TAIL PART BY THE NICKEL PLATING.

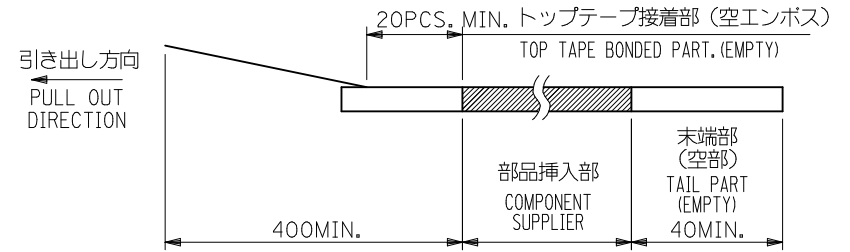
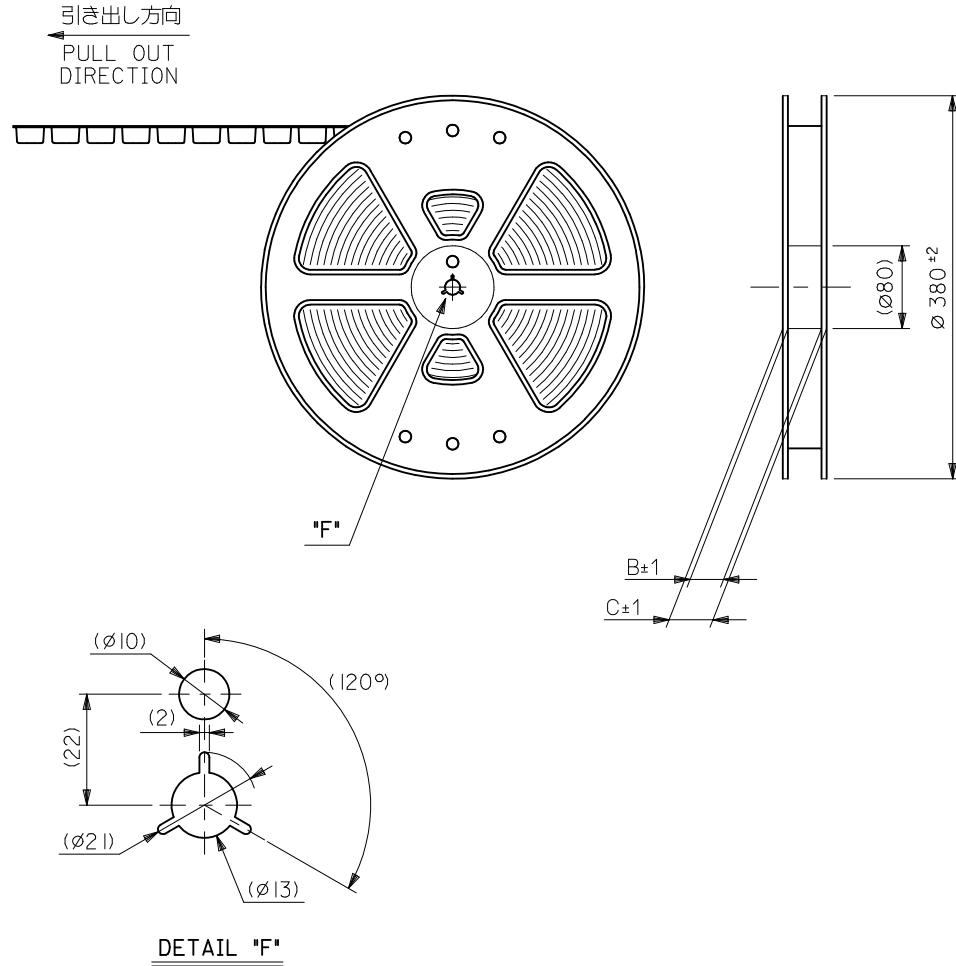
- △3 (全極数/2) = 偶数の場合に適用。
APPLY FOR (CIRCUIT/2)=EVEN.
4. 嵌合相手: 55560シリーズ, 53794シリーズ
MATE WITH: 55560 SERIES, 53794 SERIES.
5. テール平坦度は、0.1以下
TAIL COPLANARITY TO BE 0.1 MAXIMUM.

20.5	19.5	22.6	54722-0804	54722-0803	80
15.5	14.5	17.6	54722-0604	54722-0603	60
13.0	12.0	15.1	54722-0504	54722-0503	50
10.5	9.5	12.6	54722-0404	54722-0403	40
9.0	8.0	11.1	54722-0344	54722-0343	34
C	B	A	EMBSTP PKG. ORDER No. オーダー番号	MATERIAL No.	極数 CIRCUIT

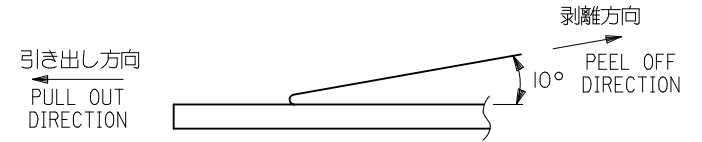
REVISED EC NO: J2017-0400 DRWN: FURUKAWA 2017/01/30 CHKD: TASAKAWA 2017/01/31 APPR: KUSUHARA01 2017/04/11	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO. 54722-***3
	0.25 UNDER	UNDER	±0.2	DRAWN BY T. ITO	DATE '03/08/20	TITLE 0.5 B-TO-B CONN REC ASSY [NI BARRIER] (HGT=1.5) -LEAD FREE- molex	SHEET NO. 2 OF 2
	0.25 OVER	0.5 UNDER	±0.2	CHECKED BY T. YAMAGUCHI	DATE '03/08/20		
	0.5 OVER	1.0 UNDER	±0.2	APPROVED BY T. YAMAGUCHI	DATE '03/08/20		
1.0 OVER	30 UNDER	±0.25	MATERIAL NO.	DOCUMENT NO.			
30 OVER		±0.3	SEE CHART		SD-54722-011		
	ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

注記 NOTES

- 製品詳細寸法については図面 SD-54722-011 を参照下さい。
RE DETAILED DIMENSION, SEE SD-54722-011
- 梱包数量：3000個/リール
NUMBER OF CONNECTORS : 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



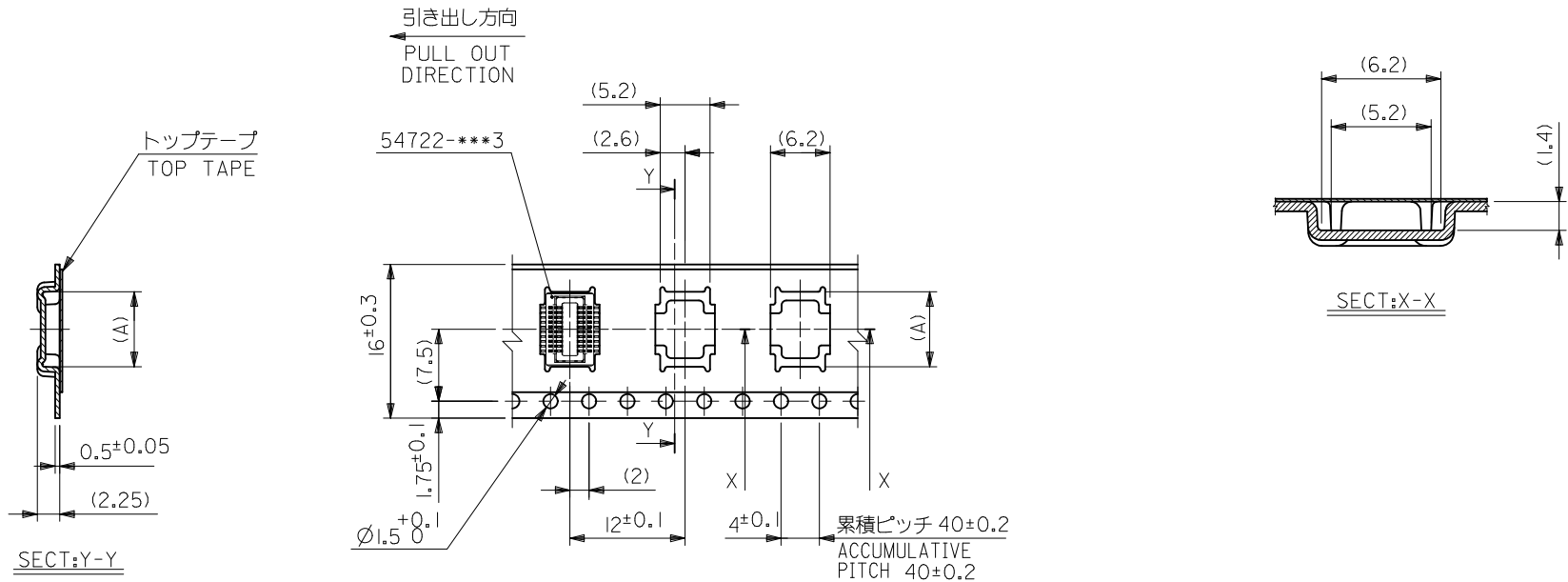
- トップテープの剥離強度：0.1 ~ 1.3N (10 ~ 130gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1 ~ 1.3N (10 ~ 130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE) : ポリプロピレン (POLYPROPYLENE)
トップテープ (TOPTAPE) : PET , PE , PEF
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>

MODEL NO. 54722-***4

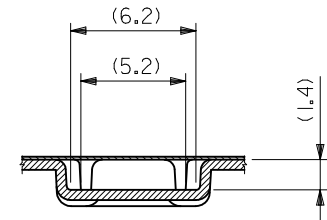
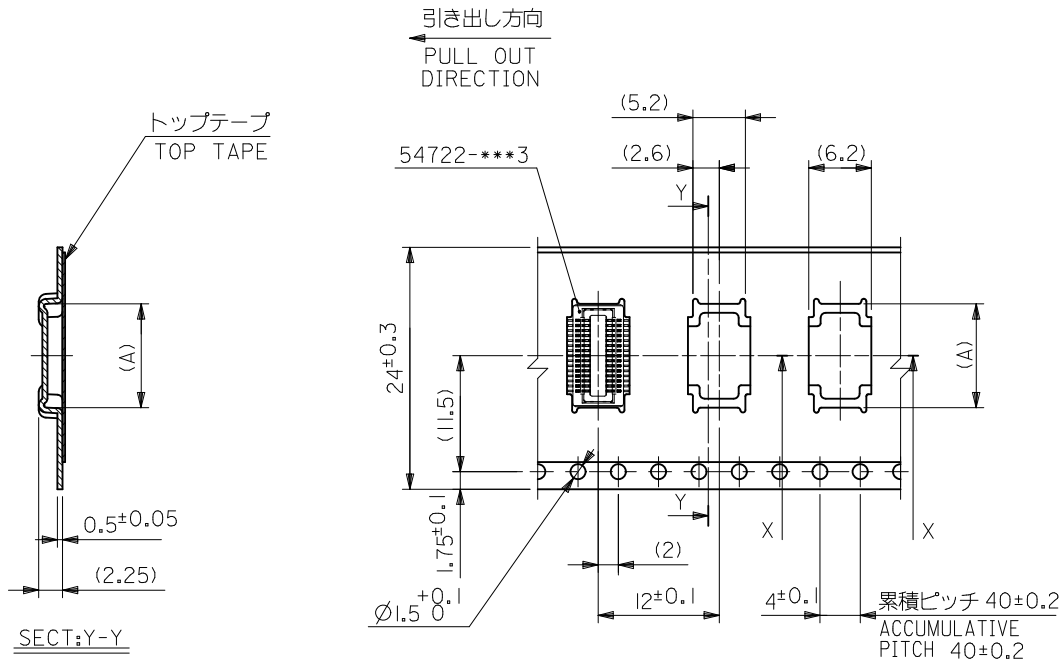
REVISED EC NO: J2010-1489 DRWN: TOSHIMA 2010/02/01 CHKD: SMARUYAMA 2010/02/02 APPR: MSASAO 2010/02/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY T. ITO	DATE '03/08/20	TITLE 0.5 B-TO-B CONN REC ASSY [NI BARRIER] EMBSTP PKG -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY T. YAMAGUCHI	DATE '03/08/20			
	30 OVER	±0.3	APPROVED BY T. YAMAGUCHI	DATE '03/08/20	MOLEX INCORPORATED		
ANGULAR ±3 °		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-54722-012			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



16mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

16	21.4	17.4	6.8	54722-0204	20
				54722-0164	16
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	MATERIAL NO.	極数 CIRCUIT

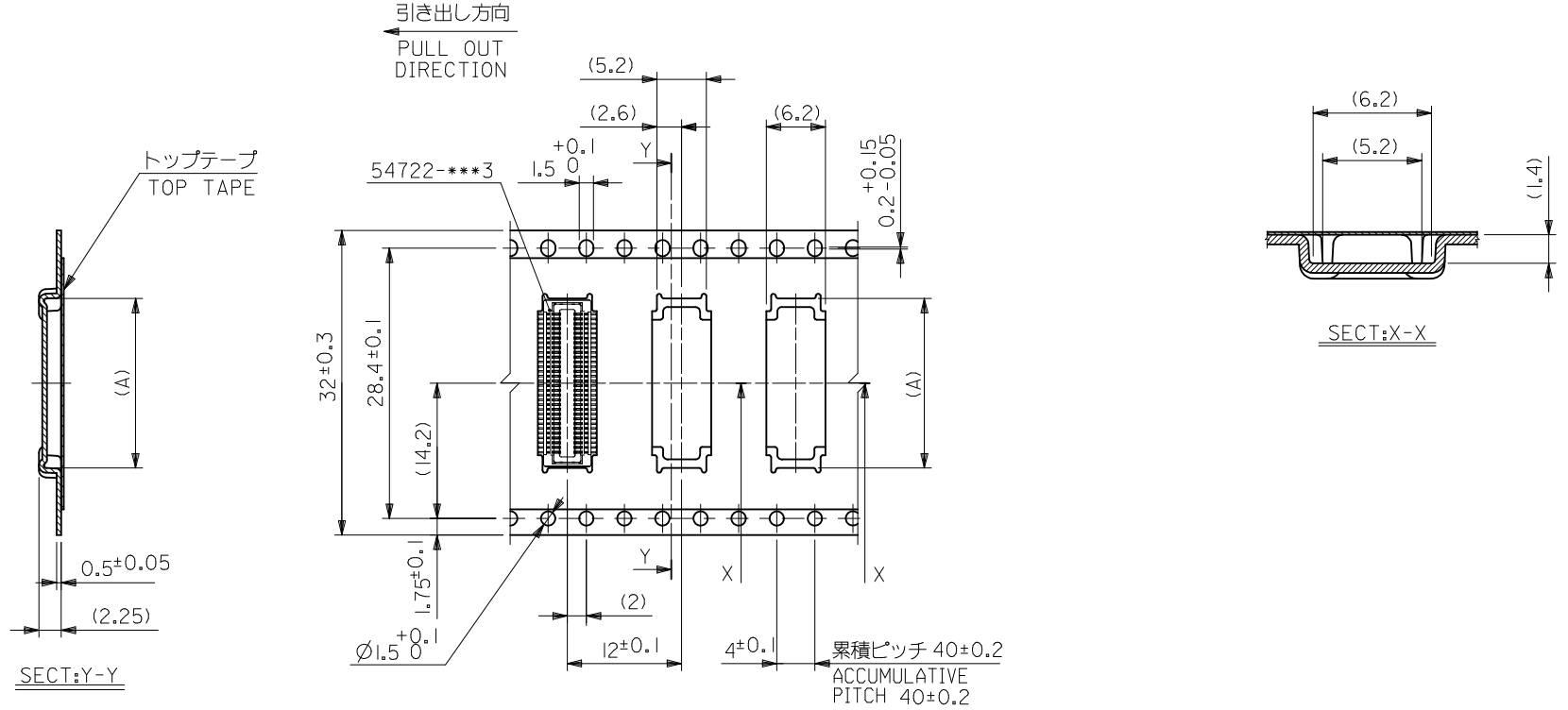
REVISED EC NO.: J2010-1489 DRWN: TOSHIMA 2010/02/01 CHK'D: SMARUYAMA 2010/02/02 APPR: MSASAO 2010/02/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	MODEL NO. 54722-***4
	10 UNDER	±0.2	DRAWN BY T. ITO	DATE '03/08/20	TITLE 0.5 B-TO-B CONN REC ASSY [NI BARRIER] EMBSTP PKG -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY T. YAMAGUCHI	DATE '03/08/20	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY T. YAMAGUCHI	DATE '03/08/20	DOCUMENT NO. SD-54722-012	
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SHEET NO. 2 OF 5
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE

24	29.4	25.4	15.3	54722-0504	50
			12.8	54722-0404	40
			11.3	54722-0344	34
			10.3	54722-0304	30
			8.8	54722-0244	24
			8.3	54722-0224	22
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	MATERIAL NO.	極数 CIRCUIT

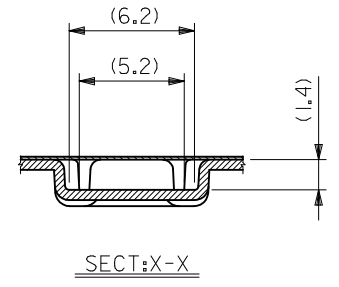
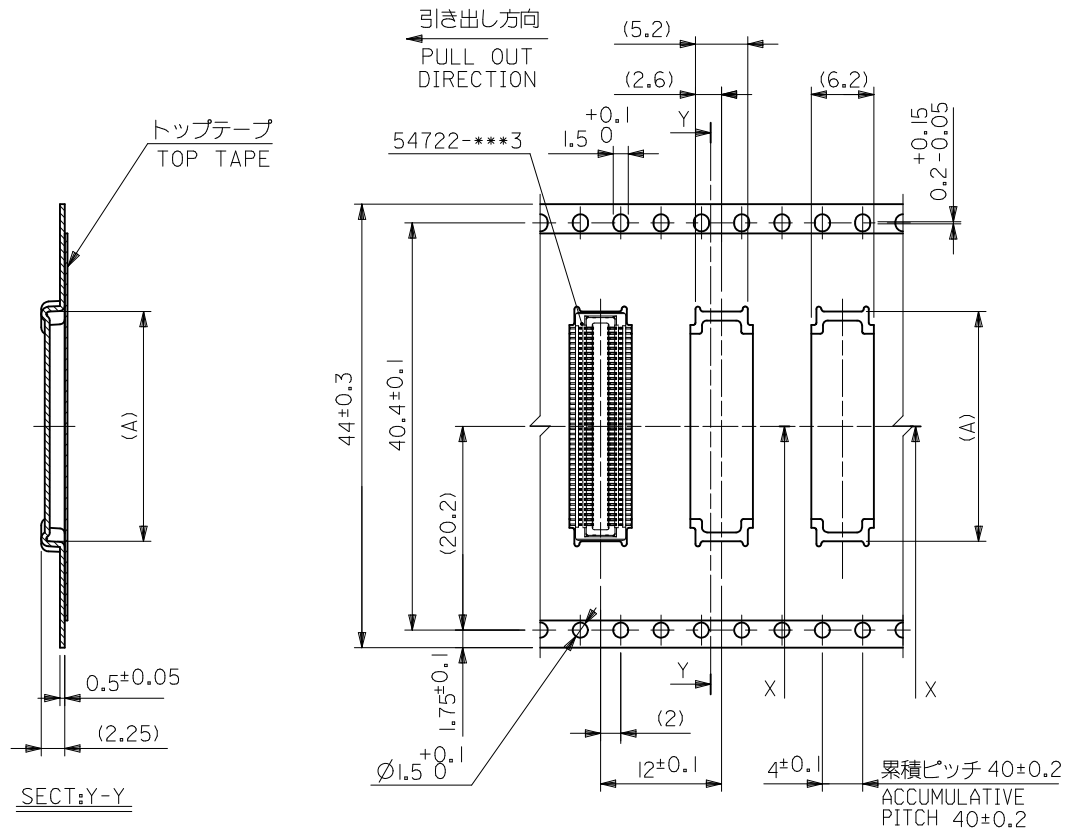
REVISED EC NO: J2010-1489 DRWN: TOSHIMA 2010/02/01 CHKD: SMARUYAMA 2010/02/02 APPR: MSASAO 2010/02/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	MODEL NO. 54722-***4
	10 UNDER	±0.2	DRAWN BY T. ITO	DATE '03/08/20	TITLE 0.5 B-TO-B CONN REC ASSY [NI BARRIER] EMBSTP PKG -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY T. YAMAGUCHI	DATE '03/08/20	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY T. YAMAGUCHI	DATE '03/08/20	DOCUMENT NO. SD-54722-012	
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	SHEET NO. 3 OF 5	
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



32mm幅キャリアテープ
32mm WIDTH CARRIER TAPE

32	37.4	33.4	17.8	54722-0604	60
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO: J2010-1489 DRWN: TOSHIMA CHKD: SMARUYAMA APPR: MSASAO	2010/02/01 2010/02/02 2010/02/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	MODEL NO.	54722-***4	
				MM ONLY	---	METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY	DATE	TITLE		
		10 OVER 30 UNDER	±0.25	T. ITO	'03/08/20	0.5 B-TO-B CONN REC ASSY [NI BARRIER] EMBSTP PKG -LEAD FREE-		
30 OVER	±0.3	CHECKED BY	DATE	APPROVED BY			MOLEX INCORPORATED MOLEX	
ANGULAR ±3 °		T. YAMAGUCHI	'03/08/20	DATE				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE	MATERIAL NO.			DOCUMENT NO.	
		T. YAMAGUCHI	'03/08/20	SEE CHART			SD-54722-012	
		SIZE A3			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			SHEET NO. 4 OF 5



44mm幅キャリアテープ
44mm WIDTH CARRIER TAPE

44	49.4	45.4	22.8	54722-0804	80
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO: J2010-1489 DRWN: TOSHIMA 2010/02/01 CHKD: SMARUYAMA 2010/02/02 APPR: MSASAO 2010/02/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	MODEL NO. 54722-***4
	10 UNDER	±0.2	DRAWN BY T. IYO	DATE '03/08/20	TITLE 0.5 B-TO-B CONN REC ASSY [NI BARRIER] EMBSTP PKG -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY T. YAMAGUCHI	DATE '03/08/20	MATERIAL NO. SD-54722-012	
	30 OVER	±0.3	APPROVED BY T. YAMAGUCHI	DATE '03/08/20	SHEET NO. 5 OF 5	
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MOLEX INCORPORATED		
		SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		